SISGM-CHAS-L3

Modular Rack Mount Hardened Layer 3 Switch

Features

- Hardware routing, RIP V2.0 and static routing
- IEC 62439-2 MRP Media Redundancy Protocol
- IEEE 1588v2 PTP clock Synchronization
- IPv4/IPv6 internet protocols
- 8K MAC Table
- HTTPS/SSH network security
- SMTP client
- IP-based bandwidth management
- Application-based QoS management
- Device Binding security function
- DOS/DDOS auto prevention
- IGMP v2/v3 IGMP snooping
- SNMP v1/v2c/v3
- RMON
- 4096 VLANs Network Management
- VLAN tagging (256 VLANS)
- Voice VLAN
- User Authentication for security
- RADIUS/TACACS+
- GRE Support
- ACL
- Supports 9.6K Bytes Jumbo Frames
- LLDP Protocol
- G.8032 V2
- MRP - Multiple Registration Protocol
- VRRP Virtual Router Redundancy Protocol
- LACP - 14 Groups
- MSTP (RSTP/STP compatible)
- TOS/DiffServ supported
- IGMP v2/v3 Snooping - 128 Groups/VLAN
- IP-based bandwidth management
- DHCP Server/Client/Relay
- DNS client proxy
- Web-based, Telnet, Console (CLI) configuration

Note: Layer 2 switch is NOT upgradeable to Layer 3

IEC61850-3 compliant managed Ethernet switch with Layer 3 static routing and RIP V2.0. With complete support of MRP Ethernet Redundancy protocol and MSTP (RSTP/STP compatible), the switch can protect your mission-critical applications from network interruptions with its fast recovery technology. Supporting a wide operating temperature from -40°C to +65°C, the switch is suitable for use in challenging environments. Remote management can be accomplished through the web-based interface and Telnet, with local management available using the console port CLI.

Modular design features: 3 Full size bays that accommodate (8) port 100/1000Base modules, 1 Half size bay that accommodates (2) or (4) port 1000/10Gb SFP modules, and 2 Power supply bays.

Specifications

Standards	IEEE 802.1p COS IEEE 802.1D IEEE 802.1s IEEE 802.1AB IEEE 802.3u IEEE 802.z IEEE 802.3x IEEE 802.3az	IEEE 802.1Q IEEE 802.1w RSTP IEEE 802.1x IEEE 802.3 IEEE 802.3ab IEEE 802.3ae IEEE 802.3ad
Port Configurations	3 Full size (8) Port Bays 1 Half size (2/4) Port Bay 2 Power Supply Bays (1) RJ-45 Console Serial Port	
Network Redundancy	O-Ring, Open-Ring, Multi-Ring, MRP – Media Redundancy Protocol, MSTP (RSTP, STP Compatible)	
Dimensions	Width: 17.32" [440 mm] Depth: 12.8" [325 mm] Height: 1.73" [44 mm] 19" Rack Mountable, 1U Requires 1U open space above and below for cooling	
Power Consumption	46 Watts (max)	
Power Input (Redundant)	VDC 48 (24~72VDC) Dual Inputs VAC 100~240VAC/100~370VAC Dual Inputs Current Overload Protection	
Fault Output	Fault Relay 1A@24VDC	
Ingress Protection	IP30	
Environment	Operating with Extended Temperature 1G or 10G SFPs: -40°C to +55°C Operating with Extended Temperature 1G SFPs only: -40°C to +65°C Humidity: 5% to 95% (non-condensing)	
Weight	14.52 lbs. [6.58 kg]	
Substation Automation	IEC61850-3, IEEE1613	
Compliance	EMI: FCC Part 15' CISPR (EN 55022) Class A, EN61000-3-2, EN61000-3-3 Environmental: EN55024, EN61000-4-2 (ESD), EN61000-4-3 (RS), EN61000-4-4 (EFT), EN61000-4-5 (Surge), EN61000-4-6 (CS), EN61000-4-8, EN61000-4-11	
Warranty	5 Years	

Ordering Information

SISGM-CHAS-L3
3 Full size bays - accommodates (8) port 100/1000Base modules
1 Half size bay - accommodates (2) or (4) port 1000/10Gb SFP module
2 Power supply bays

Optional Accessories (sold separately)

Power Supplies

SISGM-PWR-LVC
1 Power module, with cooling fans, supporting 24~72VDC

SISGM-PWR-HVC
1 Power module, with cooling fans, supporting 100 ~ 240VAC or 100 ~ 370VDC

Network Port Modules

SISGM-2P-10G-SFP
(2) Port Dual Speed 1000/10G SFP Module
Installs in Chassis Half Size Bay (1 per Chassis)

SISGM-4P-10G-SFP
(4) Port Dual Speed 1000/10G SFP Module
Installs in Chassis Half Size Bay (1 per Chassis)

SISGM-8P-1G-TX
(8) Port 10/100/1000Base-TX RJ-45 Module
Installs in Chassis Full Size Bay (3 per Chassis)

SISGM-8P-1G-SFP
(8) Port 100/1000Base-X SFP Module
Installs in Chassis Full Size Bay (3 per Chassis)

SISGM-2P-10G-SFP

SISGM-4P-10G-SFP

SISGM-8P-1G-SFP

SISGM-8P-1G-TX

Note: Product is shipped as separate modules allowing assembly and configuration during installation.